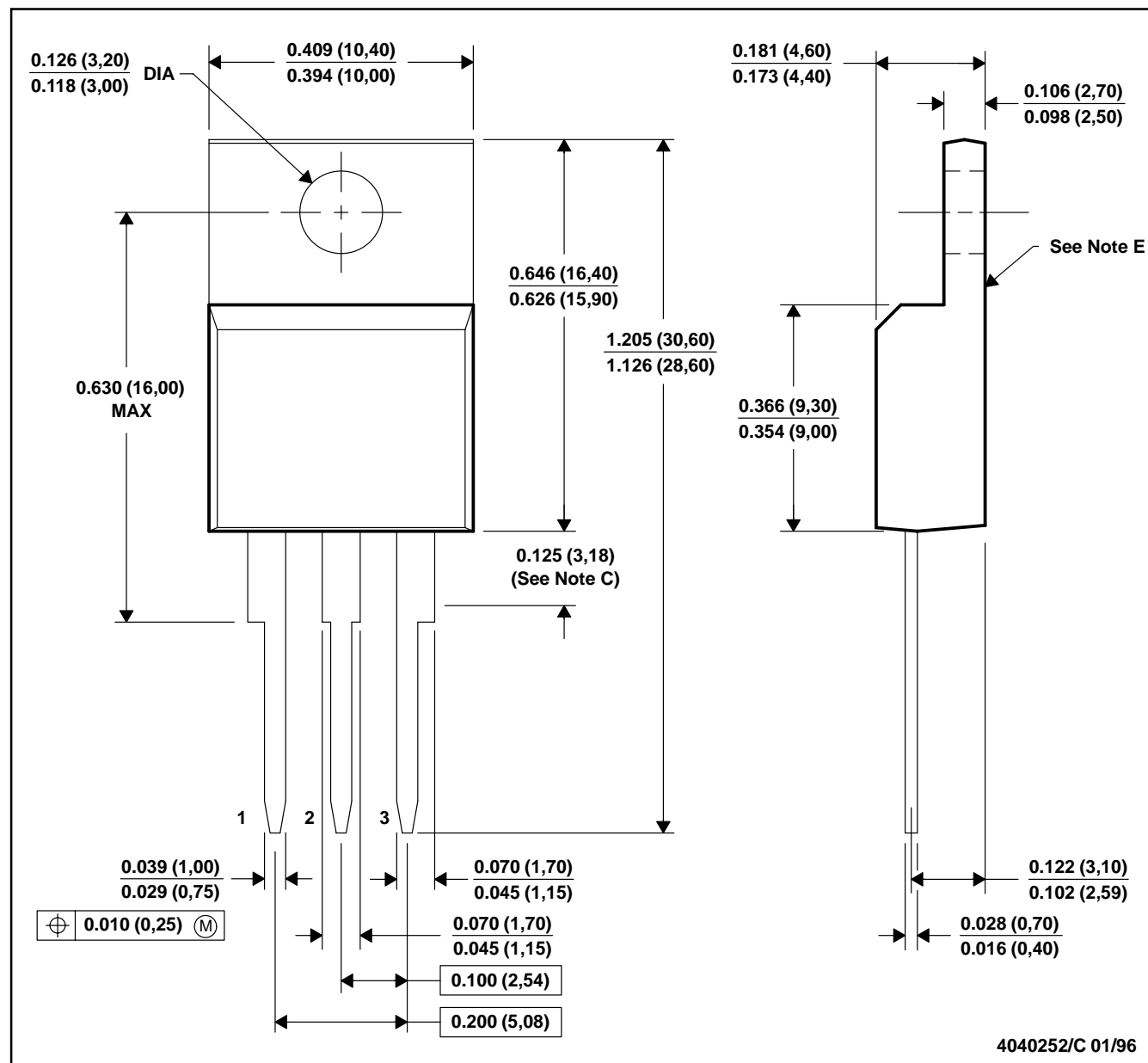


KPA (R-PSFM-T3)

PLASTIC FLANGE-MOUNT PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. Lead dimensions are not controlled within this area.
 D. All lead dimensions apply before solder dip.
 E. The mounting tab is isolated.

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